

## P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)		
	0.041 at V <sub>GS</sub> = - 4.5 V	- 4			
- 20	0.054 at V <sub>GS</sub> = - 2.5 V	- 4	12.5 nC		
	0.100 at V <sub>GS</sub> = - 1.8 V	- 4			

# SOT-363 SC-70 (6-LEADS) 6 D

Top View

### **FEATURES**

Halogen-free According to IEC 61249-2-21



- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

- Load Switch for Portable Devices
  - Cellular Phone
  - DSC
  - Portable Game Console
  - MP3
  - GPS

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 20	V	
Gate-Source Voltage		V <sub>GS</sub>	± 12	v	
	T <sub>C</sub> = 25 °C		- 4 <sup>a</sup>		
Continuous Drain Current /T 150 °C)	T <sub>C</sub> = 70 °C		- 4		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 4 <sup>a, b, c</sup>		
	T <sub>A</sub> = 70 °C		- 4 <sup>a, b, c</sup>	А	
Pulsed Drain Current (t = 300 μs)	1	I <sub>DM</sub>	- 25		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		- 2.3		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	l <sub>S</sub>	- 1.3 <sup>b, c</sup>		
	T <sub>C</sub> = 25 °C		2.8		
Mayimum Dayyar Dissination	T <sub>C</sub> = 70 °C	В	1.8	w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.6 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		1.0 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	
Soldering Recommendations (Peak Temperature)		-	260	1	

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	R <sub>thJA</sub>	60	80	°C/W	
Maximum Junction-to-Foot (Drain) Steady State		$R_{thJF}$	34	45	C/VV	

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 125 °C/W.



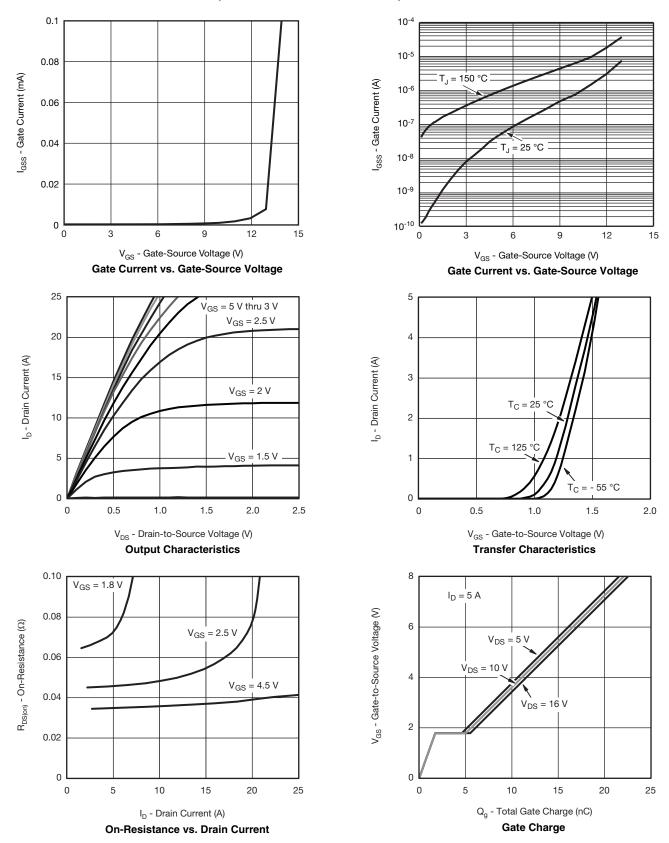
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V	
$V_{DS}$ Temperature Coefficient $\Delta V_{DS}/T_{J}$		J 050 A		- 11		m)//0/	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		2.6		mV/°C	
iate-Source Threshold Voltage $V_{GS(th)}$ $V_{DS} = V_{GS}$ , $I_D = -250 \mu A$		$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.4		- 1	V	
Gate-Source Leakage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 10 \text{ V}$			± 8		
	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 1	μΑ	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V			- 1		
	I <sub>DSS</sub>	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 15			Α	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5 A		0.034	0.041		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 4.4 A		0.045	0.054	Ω	
		V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 1 A		0.067	0.100		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 5 A		16		S	
Dynamic <sup>b</sup>	1			<b>'</b>	l .	<u> </u>	
Total Gate Charge	- Q <sub>g</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 8 V, I <sub>D</sub> = - 5 A		22	33	nC	
-				12.5	19		
Gate-Source Charge	$Q_{gs}$	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5 A		1.8			
Gate-Drain Charge	$Q_{gd}$			3.3			
Gate Resistance	$R_g$	f = 1 MHz	0.08	0.43	0.86	kΩ	
Turn-On Delay Time	t <sub>d(on)</sub>			150	225		
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V}, R_{L} = 1.4 \Omega$		300	450	-	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong -4 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		1620	2430		
Fall Time	t <sub>f</sub>			560	840		
Turn-On Delay Time	t <sub>d(on)</sub>			50	100	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V}, R_{L} = 1.4 \Omega$		90	180	1	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong -4 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		2500	3750		
Fall Time	t <sub>f</sub>			600	900	1	
<b>Drain-Source Body Diode Characterist</b>	ics						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 2.3		
Pulse Diode Forward Current	I <sub>SM</sub>				- 25	А	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = - 4 A, V <sub>GS</sub> = 0 V		- 0.85	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			18	36	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1 4 A 41/44 400 A/ T 05 00		8	16	nC	
Reverse Recovery Fall Time	ta	$I_F = -4 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		18		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			10			

#### Notes:

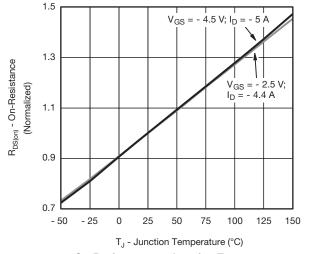
- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

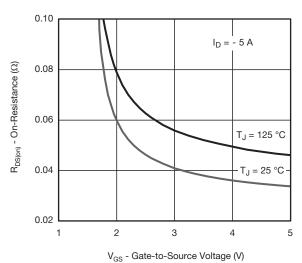




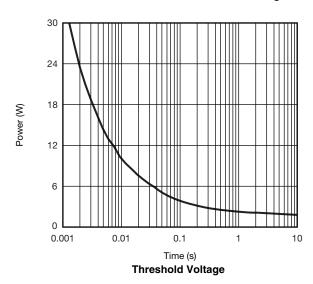


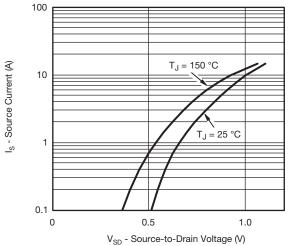


#### On-Resistance vs. Junction Temperature

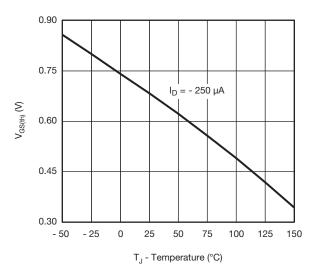


On-Resistance vs. Gate-to-Source Voltage

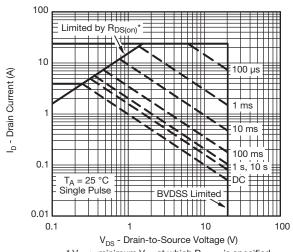




Source-Drain Diode Forward Voltage



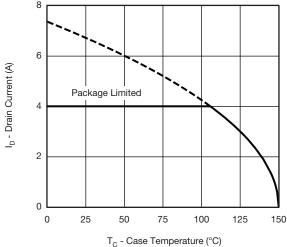
Single Pulse Power, Junction-to-Ambient



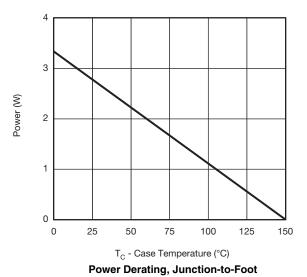
\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

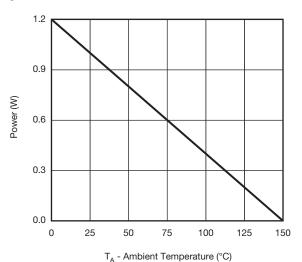
Safe Operating Area, Junction-to-Ambient





#### **Current Derating\***

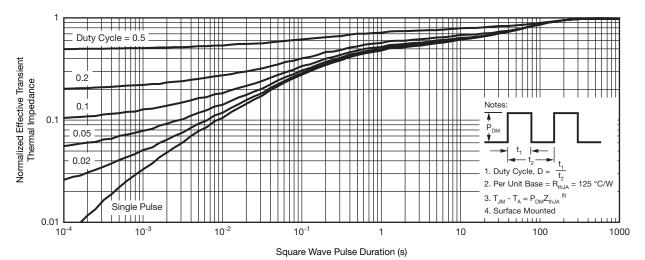




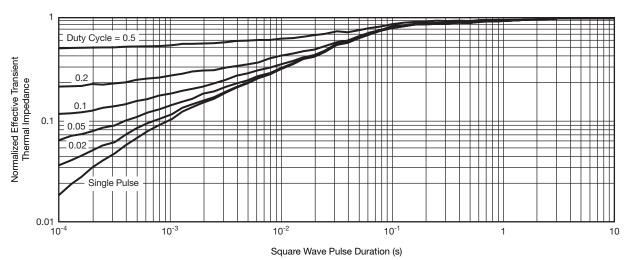
Power Derating, Junction-to-Ambient

<sup>\*</sup> The power dissipation PD is based on TJ(max) = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





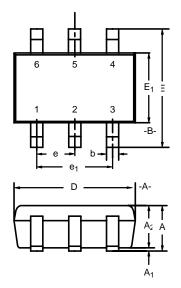
Normalized Thermal Transient Impedance, Junction-to-Ambient

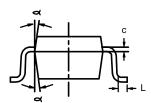


Normalized Thermal Transient Impedance, Junction-to-Foot



## SC-70: 6-LEADS

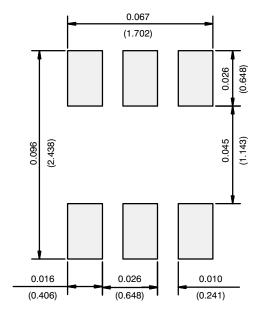




	MIL	LIMET	ERS	INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.90	-	1.10	0.035	_	0.043	
A <sub>1</sub>	_	-	0.10	-	_	0.004	
A <sub>2</sub>	0.80	-	1.00	0.031	_	0.039	
b	0.15	-	0.30	0.006	_	0.012	
С	0.10	_	0.25	0.004	-	0.010	
D	1.80	2.00	2.20	0.071	0.079	0.087	
Ε	1.80	2.10	2.40	0.071	0.083	0.094	
E <sub>1</sub>	1.15	1.25	1.35	0.045	0.049	0.053	
е	0.65BSC			0.026BSC			
e <sub>1</sub>	1.20	1.30	1.40	0.047	0.051	0.055	
L	0.10	0.20	0.30	0.004	0.008	0.012	
a	7°Nom			7°Nom			



### **RECOMMENDED MINIMUM PADS FOR SC-70: 6-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)



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